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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Thomas P. Glenn, Steven Webster, Markus K. Liebhard
Assignee: Amkor Technology, Inc.
Title: CHIP SIZE IMAGE SENSOR WIREBOND PACKAGE FABRICATION METHOD
Serial No.: 09/712,314 Filed: November 13, 2000
Examiner: Unknown Group Art 2878 Unit:
Docket No.: G0026M

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Monterey, CA
May 24, 2002

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT UNDER §1.97(b)

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicants wish to call the following documents (a copy of each is enclosed) to the attention of the Examiner:

U.S. PATENT DOCUMENTS

	Document Number	Date	Name
1)	4,801,998	01/31/89	Okuaki
2)	5,194,934	03/16/93	Yamazaki, et al.
3)	5,962,810	10/05/99	Glenn
4)	6,037,641	03/14/00	Goel
5)	6,130,448	10/10/00	Bauer, et al.

6)	6,143,588	11/07/00	Glenn
7)	6,144,107	11/07/00	Narita
8)	6,144,507	11/07/00	Hashimoto
9)	6,147,389	11/14/00	Stern, et al.
10)	6,281,568	08/28/01	Glenn, et al.

FOREIGN DOCUMENTS:

	Document Number	Date	Country
1)	JP 02278872	11/15/90	Japan
2)	JP 03209746	09/12/91	Japan
3)	JP 10223790	08/21/98	Japan

A PTO form 1449 listing these documents is enclosed.

The relevance of the non-English language documents is set forth in the accompanying English translation of the abstracts.

Citation of the above documents shall not be construed as:

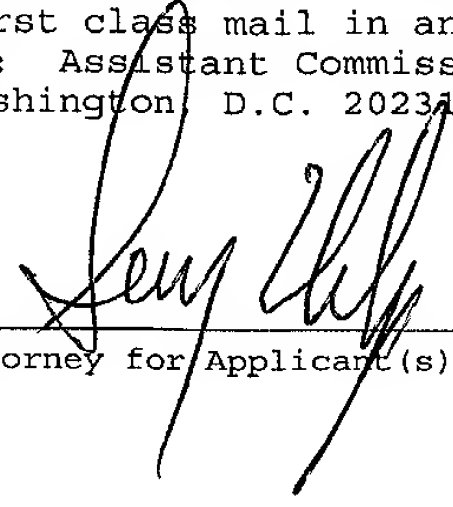
1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above; or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

The Commissioner is hereby authorized to charge any additional fees required for consideration of this Information

Disclosure Statement, and to credit any overpayment of fees to
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CERTIFICATE OF MAILING

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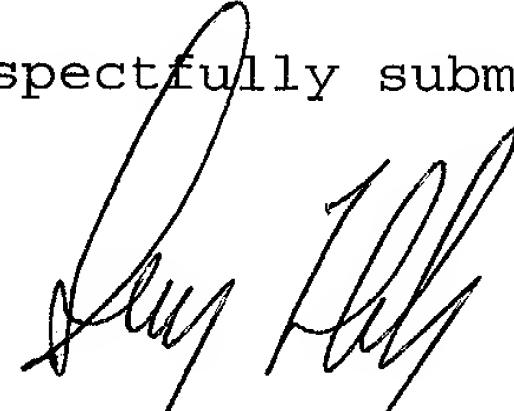


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May 24, 2002

Date of Signature

Respectfully submitted,


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